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(71) Applicant *(for all designated States except US)*: **SILVERBROOK RESEARCH PTY LTD** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU).

(72) Inventor; and

(75) Inventor/Applicant *(for US only)*: **SILVERBROOK, Kia** [AU/AU]; Silverbrook Research Pty Ltd, 393 Darling Street, Balmain, New South Wales 2041 (AU).

(74) Agent: **SILVERBROOK, Kia**; Silverbrook Research Pty Ltd, 393 Darling Street, Balmain, New South Wales 2041 (AU).

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Published:
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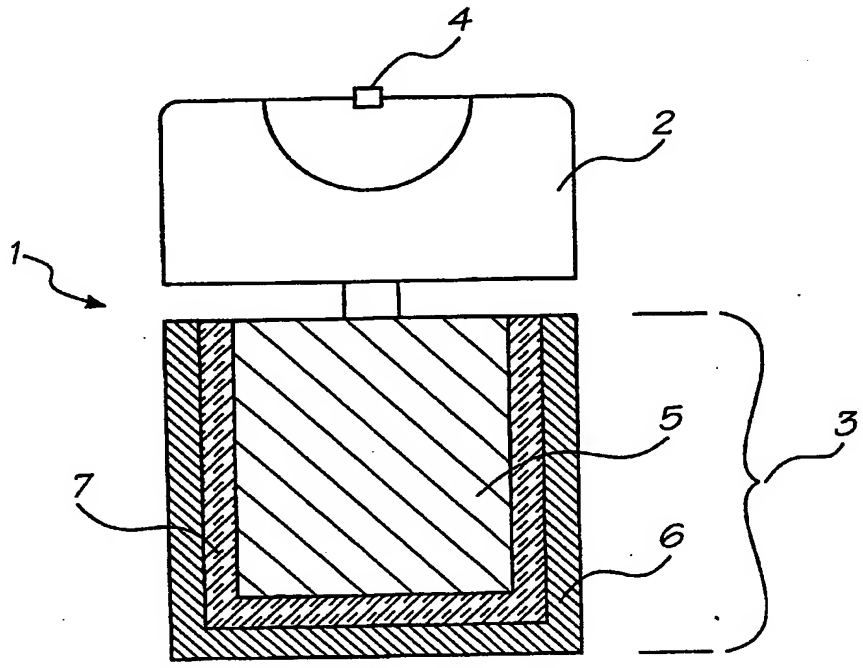
For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: THERMAL EXPANSION COMPENSATION FOR MODULAR PRINTHEAD ASSEMBLY



(57) Abstract: A method for aligning two or more printhead modules (2) mounted to a support member (3) in a printer, the method including: positioning the printhead modules (2) on the support member (3) such that they align when the support member (3) is at its operating temperature but not necessarily at other temperatures.

WO 01/66357 A1

Title

Thermal Expansion Compensation for Modular Printhead Assembly.

Field of the Invention

The present invention relates to printers, and in particular to digital inkjet printers.

Co-Pending Applications.

Various methods, systems and apparatus relating to the present invention are disclosed in the following co-pending applications filed by the applicant or assignee of the present invention on 24 May 2000:

PCT/AU00/00578	PCT/AU00/00579	PCT/AU00/00581	PCT/AU00/00580
PCT/AU00/00582	PCT/AU00/00587	PCT/AU00/00588	PCT/AU00/00589
PCT/AU00/00583	PCT/AU00/00593	PCT/AU00/00590	PCT/AU00/00591
PCT/AU00/00592	PCT/AU00/00584	PCT/AU00/00585	PCT/AU00/00586
PCT/AU00/00594	PCT/AU00/00595	PCT/AU00/00596	PCT/AU00/00597
PCT/AU00/00598	PCT/AU00/00516	PCT/AU00/00517	PCT/AU00/00511

Various methods, systems and apparatus relating to the present invention are disclosed in the following co-pending application, PCT/AU00/01445, filed by the applicant or assignee of the present invention on 27 November 2000. The disclosures of these co-pending applications are incorporated herein by cross-reference. Also incorporated by cross-reference are the disclosures of two co-filed PCT applications, PCT/AU01/00261 and PCT/AU01/00259 (deriving priority from Australian Provisional Patent Application No. PQ6110 and PQ6158). Further incorporated are the disclosures of two co-pending PCT applications filed 6 March 2001, application numbers PCT/AU01/00238 and

PCT/AU01/00239, which derive their priority from Australian Provisional Patent Application nos. PQ6059 and PQ6058.

Background of the Invention

Recently, inkjet printers have been developed which use printheads manufactured by micro-electro mechanical systems (MEMS) techniques. Such printheads have arrays of microscopic ink ejector nozzles formed in a silicon chip using MEMS manufacturing techniques. The invention will be described with particular reference to silicon printhead chips for digital inkjet printers wherein the nozzles, chambers and actuators of the chip are formed using MEMS techniques. However, it will be appreciated that this is in no way restrictive and the invention may also be used in many other applications.

Silicon printhead chips are well suited for use in pagewidth printers having stationary printheads. These printhead chips extend the width of a page instead of traversing back and forth across the page, thereby increasing printing speeds. The probability of a production defect in an eight inch long chip is much higher than a one inch chip. The high defect rate translates into relatively high production and operating costs.

To reduce the production and operating costs of pagewidth printers, the printhead may be made up of a series of separate printhead modules mounted adjacent one another, each module having its own printhead chip. To ensure that there are no gaps or overlaps in the printing produced by adjacent printhead modules it is necessary to accurately align the modules after they have been mounted to a support beam. Once aligned, the printing from each module precisely abuts the printing from adjacent modules.

Unfortunately, the alignment of the printhead modules at ambient temperature will change when the support beam expands as it heats up to the temperature it maintains during operation.

Summary of the Invention

Accordingly, the present invention provides a system for aligning two or more printhead modules mounted to a support member in a printer, the system including:

positioning the printhead modules on the support member such that they align when the support member is at its operating temperature but not necessarily at other temperatures.

Preferably, the support member is a beam and the printhead modules include MEMS manufactured chips having at least one fiducial on each;

wherein,

the fiducials are used to misalign the printhead modules by a distance calculated from:

i) the difference between the coefficient of thermal expansion of the beam and the printhead chips;

ii) the spacing of the printhead chips along the beam; and,

iii) the difference between the production temperature and the operating temperature.

Conveniently, the beam may have a core of silicon and an outer metal shell. In a further preferred embodiment, the beam is adapted to allow limited relative movement between the silicon core and the metal shell. To achieve this, the beam may include an elastomeric layer interposed between the silicon core and metal shell. In other forms, the outer shell may be formed from laminated layers of at least two different metals.

It will be appreciated that this system requires the coefficient of thermal expansion of the printhead chips to be greater than or equal to the coefficient of thermal expansion of the beam, otherwise the "gaps" left between the printhead modules as compensation at ambient temperature will not close as the beam reaches the operating temperature.

Brief Description of the Drawing

A preferred embodiment of the invention will now be described, by way of example only, with reference to the accompanying drawing in which:

Figure 1 shows a schematic cross section of a printhead assembly according to the present invention.

Detailed Description of Preferred Embodiments

Referring to the figure the printhead assembly 1 has a plurality of printhead modules 2 mounted to a support member 3 in a printer (not shown). The printhead module includes a silicon printhead chip 4 in which the nozzles, chambers, and actuators are manufactured using MEMS techniques. Each printhead chip 4 has at least 1 fiducial (not shown) for aligning the printheads. Fiducials are reference markings placed on silicon chips and the like so that they may be accurately positioned using a microscope.

According to one embodiment of the invention, the printheads are aligned while the printer is operational and the assembly is at the printing temperature. If it is not possible to view the fiducial marks while the printer is operating, an alternative system of alignment is to misalign the printhead modules on the support beam 3 such that when the printhead assembly heats up to the operating temperature, the printheads move into alignment. This is easily achieved by adjusting the microscope by the set amount of misalignment required or simply misaligning the printhead modules by the required amount.

The required amount is calculated using the difference between the coefficients of thermal expansion of the printhead modules and the support beam, the length of each individual printhead module and the difference between ambient temperature and the operating temperature. The printer is designed to operate with acceptable module alignment within a temperature range that will encompass the vast majority of environments in which it expected to work. A typical temperature range may be 0^0C to 40^0C. During operation, the operating temperature of the printhead rise a fixed amount above the ambient temperature in which the printer is operating at the time. Say this increase is 50^0C, the temperature range in which the alignment of the modules must be within the acceptable limits is 50^0C to 90^0C. Therefore, when misaligning the modules during production of the printhead, the production temperature should be carefully maintained at 20^0C to ensure that the alignment is within acceptable limits for the entire range of predetermined ambient temperatures (i.e. 0^0C to 40^0C).

To minimize the difference in coefficient of thermal expansion between the printhead modules and the support beam 3, the support beam has a silicon core 5 mounted within a metal channel 6. The metal channel 6 provides a strong cost effective structure for mounting within a printer while the silicon core provides the mounting points for the printhead modules and also helps to reduce the coefficient of thermal expansion of the support beam 3 as a whole. To further isolate the silicon core from the high coefficient of thermal expansion in the metal channel 6 an elastomeric layer 7 is positioned between the core 5 and the channel 6. The elastomeric layer 7 allows limited movement between the metal channel 6 and the silicon core 5.

The invention has been described with reference to specific embodiments. The ordinary worker in this field will readily recognise that the invention may be embodied in many other forms.

CLAIMS :-

1. A method for aligning two or more printhead modules mounted to a support member in a printer, the method including:

positioning the printhead modules on the support member such that they align when the support member is at its operating temperature but not necessarily at other temperatures.

2. A system for aligning a plurality of printhead modules mounted on a support member in a printer wherein the support member is a beam and the printhead modules include MEMS manufactured chips having at least one fiducial on each;

wherein,

the fiducials are used to misalign the printhead modules at ambient temperature by a distance calculated from:

i) the difference in coefficient thermal expansion between the beam and the printhead chips;

ii) the spacing of the printhead chips along the beam; and,

iii) the difference between the production temperature and the operating temperature.

3. A system for aligning a plurality of printhead modules mounted to a support member and a printer according to claim 2 wherein the beam has a core of silicon and an outer metal shell.

4. A system for aligning a plurality of printhead modules mounted to a support member in a printer according to claim 3 wherein the beam is adapted to allow limited relative movement between the silicon core and the metal shell.

5. A system for aligning a plurality of printhead modules mounted to a support member in a printer according to claim 4 wherein the beam has an elastomeric layer between the silicon core and metal shell to permit the limited relative movement.

6. A system for aligning a plurality of printhead modules mounted to a support member in a printer according to claim 5 wherein the outer shell is formed from laminated layers of at least two different metals.

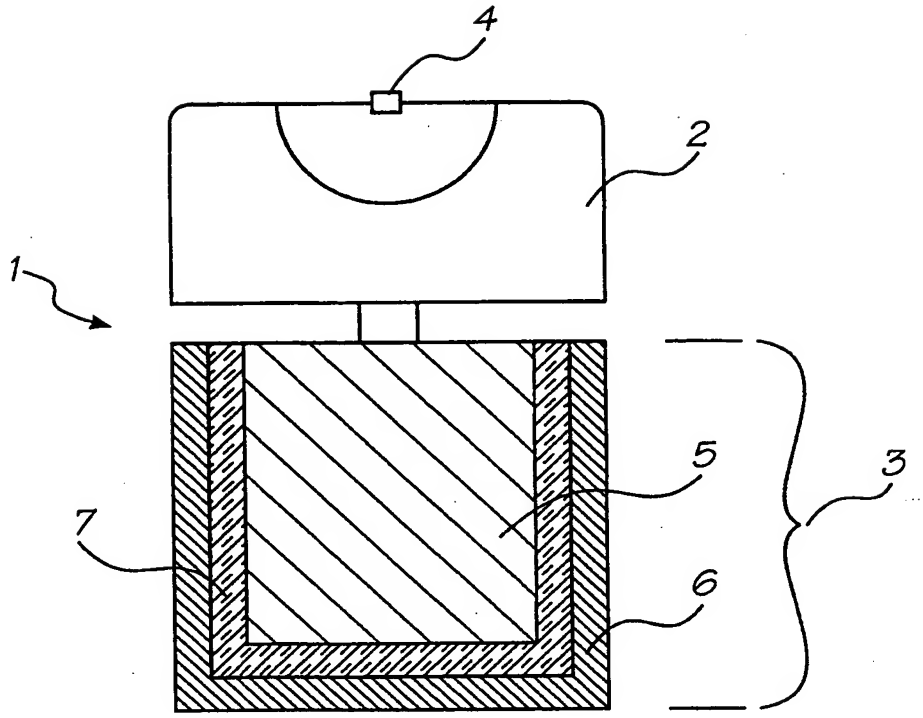


FIG. 1

INTERNATIONAL SEARCH REPORT

International application No.
PCT/AU01/00260

A. CLASSIFICATION OF SUBJECT MATTER

Int. Cl. [7]: B41J 2/14

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

IPC: B41J 2/-. 29/-

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

WPAT: IPC as above with keywords: MEM, printhead, align, temperature and similar terms

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
P,A	Derwent Abstract Accession No. 2000-676139/66, Class P75; T04, JP 2000280496 A (TOKYO ELECTRIC CO LTD) 10 October 2000 Abstract	
A	Derwent Abstract Accession No. 99-147317/13, Class P75, JP 11-010861 A (BROTHER KOGYO KK) 19 January 1999 Abstract	

☐ Further documents are listed in the continuation of Box C ☒ See patent family annex

* Special categories of cited documents:

"A" document defining the general state of the art which is not considered to be of particular relevance

"E" earlier application or patent but published on or after the international filing date

"L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified)

"O" document referring to an oral disclosure, use, exhibition or other means

"P" document published prior to the international filing date but later than the priority date claimed

"T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention

"X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone

"Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art

"&" document member of the same patent family

Date of the actual completion of the international search	Date of mailing of the international search report
22 May 2001	1 June 2001
Name and mailing address of the ISA/AU	Authorized officer
AUSTRALIAN PATENT OFFICE PO BOX 200, WODEN ACT 2606, AUSTRALIA E-mail address: pct@ipaustralia.gov.au Facsimile No. (02) 6285 3929	**JAGDISH WABLE** Telephone No : (02) 6283 2638

INTERNATIONAL SEARCH REPORT
Information on patent family members

International application No.
PCT/AU01/00260

This Annex lists the known "A" publication level patent family members relating to the patent documents cited in the above-mentioned international search report. The Australian Patent Office is in no way liable for these particulars which are merely given for the purpose of information.

Patent Document Cited in Search Report		Patent Family Member
JP	2000280496	NONE
JP	11010861	NONE

END OF ANNEX